ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and	nposition De 5. IPC, Bannockt Pan-American co	c laration ourn, Illinois. <i>A</i> opyright conve	All rights reserved u ntions.	nder both	This docume level parts, th	ent is a declaration entities of the declaration entities	on of the substan	ces within the ma wer level materia	anufacturer list als for which t	ed item. Note: if he manufacturer	f the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information													
Company name* Company unique ID			ique ID		Unique ID Authority			Res	Response Date*				
onsemi					2024-05-02								
Contact Name Title - Contact			ct]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards Produ			Product Enviro Compliance			NA			Pro	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			sentative]	Phone - Representative* Email - Representative*							
Product-Env-Stewards Product Enviro			ro Compliance		NA Product-Env-Stewards@onsemi.com					om			
Requester Item Number			Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	STK534	STK534U362C-E 3phase inverter HIC		IC		2024-05-02		VN2		13900.0	mg	Each	
Ianufacturing Proccess Inform	nation					-		-		-			
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base Allo		Alloy J	J-STD-020 MSI	L Rating	Peak Proce	ss Body Temper	Body Temperature Max Time at Peak		erature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU A		CU Alloy	I	NA		0	С	30	se	econds 3			
omments													
or more information regarding mater	ial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such completes this form. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rise is an advent with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or member state agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.												
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.												
Supplier Digital Signature R	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

sigma range of distribution unless otherwise noted).

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Chip Parts	30.72	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0092	mg
			Supplier	Silver (Ag)	7440-22-4		1.0691	mg
			Supplier	Epoxy resins	129915-35-1		0.3164	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068- 38-6		0.0246	mg
			Supplier	Tin (Sn)	7440-31-5		1.0476	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0276	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.8325	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		7.1731	mg
			Supplier	Phenolic resins	Proprietary Data		0.0553	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0092	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		17.5503	mg
			В	Nickel (Ni)	7440-02-0		1.2749	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.1505	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0092	mg
			Supplier	Copper (Cu)	7440-50-8		1.1704	mg
DBC	3843.72	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1499.0508	mg
			В	Nickel (Ni)	7440-02-0		38.4372	mg
			Supplier	Copper (Cu)	7440-50-8		2306.2319	mg
Die	29.39	mg	Supplier	Silicon (Si)	7440-21-3		29.39	mg
Die Attach	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.0549	mg
			В	Antimony (Sb)	7440-36-0		0.0051	mg
Heat Sink	850.31	mg	Supplier	Silver (Ag)	7440-22-4		136.0496	mg
			Supplier	Copper (Cu)	7440-50-8		714.2604	mg
Lead Frame	515.44	mg	Supplier	Tin (Sn)	7440-31-5		0.3093	mg
			Supplier	Copper (Cu)	7440-50-8		515.1307	mg
Mold Compound-Black	8502.16	mg		Brominated epoxy resin	proprietary data		20.4052	mg
			Supplier	Phenolic Resin	Proprietary Data		440.4119	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		15.3039	mg
			Supplier	Carbon Black (C)	1333-86-4		34.8589	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		596.0015	mg

			Supplier	Fused Silica (SiO2)	60676-86-0	5585.9189	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	935.2376	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	874.022	mg
Plating	1.03	mg	Supplier	Tin (Sn)	7440-31-5	1.03	mg
Solder Ball	61.83	mg	Supplier	Silver (Ag)	7440-22-4	1.8734	mg
			Supplier	Tin (Sn)	7440-31-5	59.5176	mg
			В	Antimony (Sb)	7440-36-0	0.0185	mg
			Supplier	Copper (Cu)	7440-50-8	0.4204	mg
Wire Bond - Al	65.34	mg	Supplier	Aluminum (Al)	7429-90-5	65.34	mg